Filename: PMP30236RevC - BoM.xls

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## IEXAS INSTRUM

## PMP30236 REV C Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	C1, C12	2	2200pF	GRM188R71H222KA01D	MuRata	CAP, CERM, 2200 pF, 50 V, +/- 10%, X7R, 0603	0603
2	C2, C23	2	1uF	GRM21BR71H105KA12L	MuRata	CAP, CERM, 1 µF, 50 V, +/- 10%, X7R, 0805	0805
3	C6, C7,	6	10uF	GRM32ER71H106KA12L	MuRata	CAP, CERM, 10 μF, 50 V, +/- 10%, X7R, 1210	1210
	C10, C20, C101, C102						
4	C8, C11,	3	0.1uF	GRM188R71H104KA93D	MuRata	CAP, CERM, 0.1 µF, 50 V, +/- 10%, X7R, 0603	0603
	C18						
5	C13	1	2.2uF	GRM31CR71H225KA88L	MuRata	CAP, CERM, 2.2 μF, 50 V, +/- 10%, X7R, 1206	1206
6	C14	1	4.7uF	GRM21BR71C475KA73L	MuRata	CAP, CERM, 4.7 µF, 16 V, +/- 10%, X7R, 0805	0805
7	C15	1	0.33uF	GRM188R71C334KA01D	MuRata	CAP, CERM, 0.33 μF, 16 V, +/- 10%, X7R, 0603	0603
8	C17	1	0.01uF	GRM188R72A103KA01D	MuRata	CAP, CERM, 0.01 μF, 100 V, +/- 10%, X7R, 0603	0603
9	D1	1	60V	PDS560-13	Diodes Inc.	Diode, Schottky, 60 V, 5 A, PowerDI5	PowerDI5
10	D2	1	16V	DDZ16Q-7	Diodes Inc.	Diode, Zener, 6.2 V, 500 mW, AEC-Q101, SOD-123	SOD-123
11	D3	1	100V	SBAV99LT1G	ON Semiconductor	Diode, Standard Recovery Rectifier, 100 V, 0.715 A, AEC-Q101, SOT-23	SOT-23
12	J1, J2	2		282856-2	TE Connectivity	Therminal Block, 5 mm, 2-pole, Tin, TH	TH, 2-Leads, Body 10x10mm, Pitch 5mm
13	J4	1		PBC02SAAN	Sullins Connector Solutions	Header, 100mil, 2x1, Gold, TH	Sullins 100mil, 1x2, 230 mil above insulator
14	J5	1		PBC03SAAN	Sullins Connector Solutions	Header, 100mil, 3x1, Gold, TH	PBC03SAAN
15	J7	1		PRPC008DAAN-RC	Sullins Connector Solutions	Header, 2.54mm, 8x2, Gold, TH	Header, 2.54mm, 8x2, TH
16	J8, J9	2		1040	Keystone	TEST POINT SLOTTED .118", TH	Test point, TH Slot Test point
17	L1, L101	2	2.2uH	IHLP4040DZER2R2M01	Vishay-Dale	Inductor, Shielded Drum Core, Powdered Iron, 2.2 µH, 12 A, 0.009 ohm, SMD	IHLP-4040DZ
18	Q1	1	-40V	DMP4013LFGQ	Diodes Inc.	MOSFET, P-CH, -40 V, -8.8 A, AEC-Q101, PowerDI3333-8	PowerDI3333-8
19	Q2	1	40V	SQS484EN	Vishay-Siliconix	MOSFET, N-CH, 40 V, 16 A, AEC-Q101, PowerPAK 1212	PowerPAK 1212
20	R2	1	2.00	ERJ-14BQF2R0U	Panasonic	RES, 2.00, 1%, 0.5 W, AEC-Q200 Grade 0, 1210	1210
21	R3	1	49.9k	CRCW060349K9FKEA	Vishay-Dale	RES, 49.9 k, 1%, 0.1 W, 0603	0603
22	R4	1	3.3	CRCW06033R30JNEA	Vishay-Dale	RES, 3.3, 5%, 0.1 W, 0603	0603
23	R7, R10, R11, R14	4	0	CRCW06030000Z0EA	Vishay-Dale	RES, 0, 5%, 0.1 W, 0603	0603
24	R8	1	0.006	WSL20106L000FEA18	Vishay-Dale	RES, 0.006, 1%, 1 W, 2010	2010
25	R9	1	100	CRCW0603100RFKEA	Vishay-Dale	RES, 100, 1%, 0.1 W, 0603	0603
26	R15	1	53.6k	CRCW060353K6FKEA	Vishay-Dale	RES, 53.6 k, 1%, 0.1 W, 0603	0603
27	R16	1	71.5k	CRCW060371K5FKEA	Vishay-Dale	RES, 71.5 k, 1%, 0.1 W, 0603	0603
28	R17	1	54.9k	CRCW060354K9FKEA	Vishay-Dale	RES, 54.9 k, 1%, 0.1 W, 0603	0603
29	R18	1	41.2k	CRCW060341K2FKEA	Vishay-Dale	RES, 41.2 k, 1%, 0.1 W, 0603	0603

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
30	R19	1	29.4k	CRCW060329K4FKEA	Vishay-Dale	RES, 29.4 k, 1%, 0.1 W, 0603	0603
31	R20	1	9.53k	CRCW06039K53FKEA	Vishay-Dale	RES, 9.53 k, 1%, 0.1 W, 0603	0603
32	R21	1	90.9k	CRCW060390K9FKEA	Vishay-Dale	RES, 90.9 k, 1%, 0.1 W, 0603	0603
33	R22, R23	2	10.0	CRCW060310R0FKEA	Vishay-Dale	RES, 10.0, 1%, 0.1 W, 0603	0603
34	R24	1	19.1k	CRCW060319K1FKEA	Vishay-Dale	RES, 19.1 k, 1%, 0.1 W, 0603	0603
35	TP1	1		5003	Keystone	Test Point, Miniature, Orange, TH	Orange Miniature
							Testpoint
36	TP2, TP3	2		5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature
							Testpoint
37	TP4	1		5002	Keystone	Test Point, Miniature, White, TH	White Miniature
							Testpoint
38	TP5	1		5004	Keystone	Test Point, Miniature, Yellow, TH	Yellow Miniature
							Testpoint
39	TP6	1		5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature
							Testpoint
40	U1	1		LM5150QRUMRQ1	Texas Instruments	Wide VIN Automotive Low IQ Boost Controller, RUM0016C (WQFN-16)	RUM0016C

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